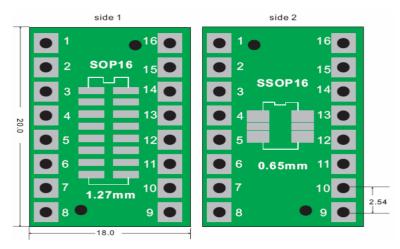


## No. 1568248



## **Technical data**

## Function: SOP16 & SSOP16 package to DIP

## **Technical Data:**

Board Material	FR-4
SMD package	SOP16 (side 1)
	SSOP16 (side 2)
Pitch	1.27 (Side 1)
	0.65 (Side 2)
Board Thickness	1.6mm ± 0.1mm
Surface Technioque	Spray tin 5-8um
Copper Thickness	35um ± 5um
Solderability	260°C at 3s - 1.1%
Flammability	V-0
Surface Resistivity	1.0 x 106 MΩ
Volume Resistivity	1.0 x 108 MΩ - cm
Arc Resistance	125sec.

This is a publication by Conrad Electronic SE, Klaus-Conrad-Str. 1, D-92240 Hirschau (www.conrad.com). All rights including translation reserved. Reproduction by any method, e.g. photocopy, microfilming, or the capture in electronic data processing systems require the prior written approval by the editor. Reprinting, also in part, is prohibited. This publication represents the technical status at the time of printing.

© Copyright 2020 by Conrad Electronic SE. Version: 01 Date: 2020-03-20